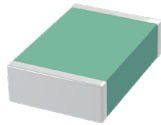


APPLICATIONS

- Typical uses : timing, precision circuitry, filtering



FEATURES

- Ultra stable temperature compensating class I ceramic
- Custom voltage, package size, capacitance value on request
- Tested in accordance to CECC 32100 and AEC-Q200
- CECC 30600 et NFC 83-131 compliant
- Available in stack or radial
- Surface coating can be necessary to prevent surface arcing

ELECTRICAL PARAMETERS

ELECTRICAL CHARACTERISTICS :

at + 25°C unless otherwise specified

OPERATING TEMPERATURE :

- 55°C, + 125°C

TEMPERATURE COEFFICIENT :

± 30ppm with 0Vdc applied

DISSIPATION FACTOR :

≤ 1.10-3 at 1Vrms and 1MHz for values ≤ 1000pF

≤ 1.10-3 at 1Vrms and 1KHz for values > 1000pF

INSULATION RESISTANCE (IR) :

25°C/Un 10⁵ MOhm or 1000 Ohm-Farad whichever is less

125°C/Un 10⁴ MOhm or 100 Ohm-Farad whichever is less

DIELECTRIC STRENGTH TEST :

Performed per method 103 of EIA 198-2-E

1.2Un for 5s with 50mA max charging current

QUICK REFERENCE DATA

	0805	1206	1210	1808	1812	1825	2220	2225	3640	4040	5440	5550	6660	8060	80150
Min	0.1 pF	0.4 pF	0.4 pF	1.0 pF	1.0 pF	1.0 pF	1.0 pF	1.0 pF	10 pF	10 pF	10 pF	10 pF	10 pF	10 pF	22 pF
1KV	560 pF	1.8 nF	4.7 nF	4.7 nF	12 nF	27 nF	27 nF	33 nF	100 nF	100 nF	120 nF	180 nF	270 nF	330 nF	820 nF
1.5KV	220 pF	680 pF	1.8 nF	1.8 nF	5.6 nF	15 nF	18 nF	22 nF	56 nF	68 nF	82 nF	100 nF	150 nF	180 nF	470 nF
2KV	82 pF	270 pF	820 pF	680 pF	1.8 nF	3.9 nF	3.9 nF	4.7 nF	12 nF	15 nF	18 nF	27 nF	39 nF	47 nF	120 nF
3KV		120 pF	330 pF	330 pF	1.0 nF	2.2 nF	2.2 nF	2.7 nF	6.8 nF	8.2 nF	10 nF	12 nF	18 nF	22 nF	56 nF
4KV		56 pF	180 pF	150 pF	390 pF	820 pF	1.0 nF	1.2 nF	2.7 nF	3.3 nF	4.7 nF	5.6 nF	8.2 nF	10 nF	27 nF
5KV				100 pF	220 pF	470 pF	470 pF	560 pF	1.5 nF	1.8 nF	2.2 nF	3.3 nF	4.7 nF	5.6 nF	12 nF
8KV							180 pF	220 pF	680 pF	680 pF	1.0 nF	1.2 nF	1.8 nF	2.2 nF	5.6 nF
10KV									390 pF	470 pF	680 pF	820 pF	1.2 nF	1.5 nF	3.3 nF
12KV									270 pF	330 pF	390 pF	560 pF	820 pF	1.0 nF	2.2 nF
15KV									150 pF	180 pF	220 pF	330 pF	470 pF	560 pF	1.2 nF

ORDERING INFORMATION

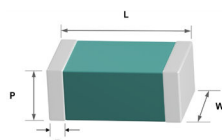
5440	A	101	K	H	X	B	-
SIZE	DIELECTRIC	CAPACITANCE	TOLERANCE	VOLTAGE	TERMINATION	PACKAGING	SPECIAL PARAMETERS
0805 1206 1210 1808 1812 1825 2220 2225 3033 3640 4040 4055 5440 5550 6660 8060 80150	A = NPO	Expressed in picofarads (pF). The first two digits are significant, the third digit gives the number of noughts. Example : 102 = 1 000pF	A = ±0.5% if > 10pF and ±0.05pF si < 10pF B = ± 0.1pF C = ± 0.25pF D = ± 0.5pF E = 0.1% F = ± 1% G = ± 2% J = ± 5% K = ± 10%	G = 1KV O = 1.5KV H = 2KV T = 2.5KV I = 3KV K = 4KV L = 5KV 6 = 6KV 8 = 8KV 10 = 10KV 12 = 12KV 15 = 15KV	X = Nickel Tin F = Palladium-Silver P = Polymer Tin C = Copper Tin W = Nickel Gold Q = Solderable Silver	B = Reel V = Bulk	- BM = BME Dxx = Reliability spec Exx = Sorting spec

For other sizes, voltage, tolerance contact us

DIMENSIONS IN MILLIMETERS

	0805	1206	1210	1808	1812	1825	2220	2225	3640	4040	5440	5550	6660	8060	80150
Length (L)	2.00 ± 0.2	3.20 ± 0.2	3.20 ± 0.2	4.60 ± 0.3	4.60 ± 0.3	4.60 ± 0.4	5.60 ± 0.4	5.60 ± 0.4	9.15 ± 0.8	10.20 ± 0.8	13.70 ± 1.0	14.00 ± 1.0	16.80 ± 1.0	20.30 ± 1.0	20.30 ± 1.0
Width (W)	1.25 ± 0.2	1.60 ± 0.2	2.50 ± 0.2	2.00 ± 0.2	3.20 ± 0.2	6.35 ± 0.3	5.10 ± 0.4	6.35 ± 0.4	10.20 ± 0.8	10.20 ± 0.8	10.20 ± 1.0	12.70 ± 1.0	15.20 ± 1.0	15.20 ± 1.0	38.10 ± 1.0
Thickness max (T)	1.40	1.70	2.50	2.20	3.30	3.60	4.00	4.00	4.00	4.00	4.00	4.00	4.00	4.00	4.00
Termination (P)	Min Max	0.25 0.70	0.25 0.70	0.25 0.80	0.25 0.80	0.25 0.80	0.25 0.80	0.25 1.00	0.80 1.50	0.80 1.50	0.80 1.50	0.80 1.50	0.80 1.50	0.80 1.50	0.80 1.50

For P termination (Polymer type) add 0.20mm to all dimensions



STANDARD SIZE : 0805 to 3640

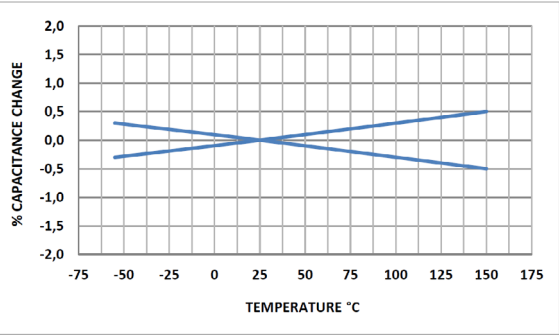
[illegible]

STANDARD SIZE : 4040 to 80150

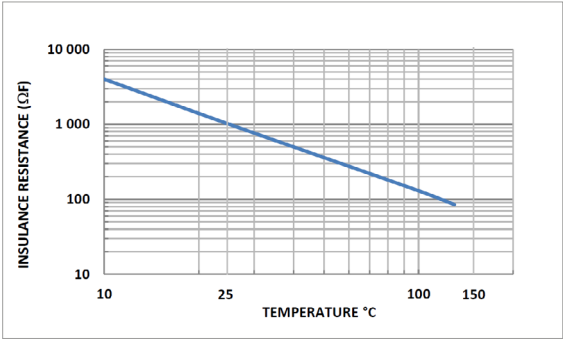
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TYPICAL CHARACTERISTICS

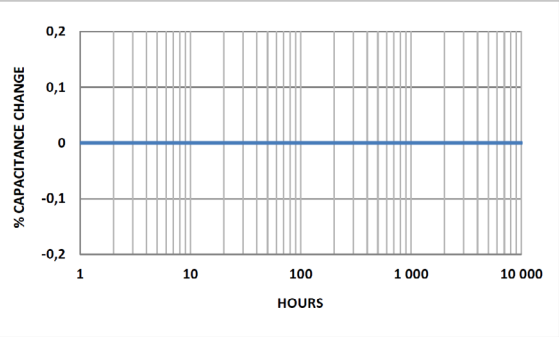
NPO Temperature coefficient of capacitance



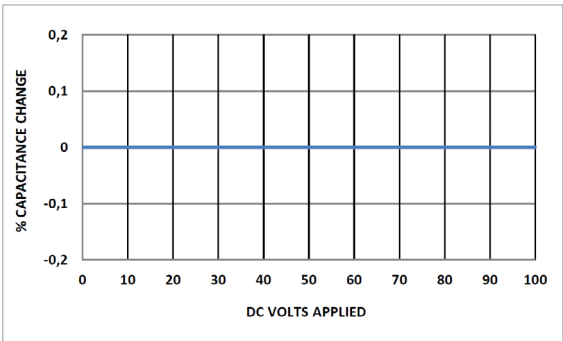
NPO Insulation resistance vs. temperature



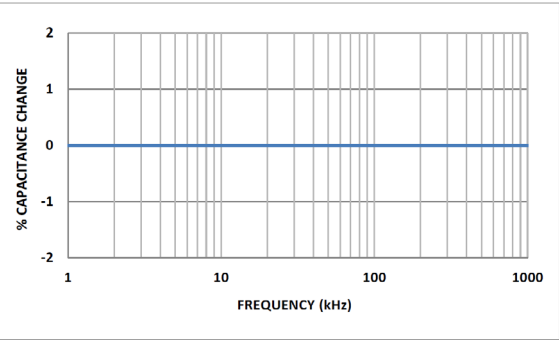
NPO Aging rate



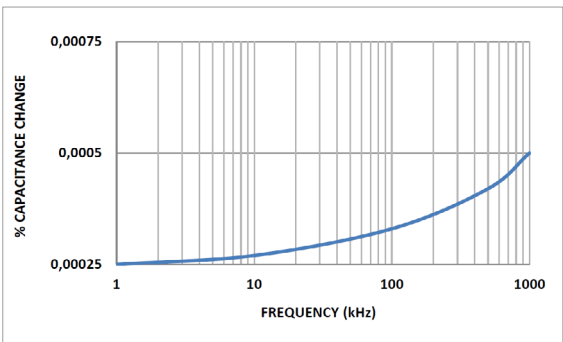
NPO Voltage coefficient of capacitance



NPO Change of Capacitance with Frequency



NPO Dissipation factor vs. frequency



STORAGE

To prevent the damage of solderability of terminations, the following storage conditions are recommended :

Indoors under 5 ~ 40°C and 20% ~ 70% RH.

No harmful gases containing sulfuric acid, ammonia, hydrogen sulfide or chlorine.

Packaging should not be opened until the capacitors are required for use. If opened, the pack should be re-sealed as soon as possible. Taped products should be stored out of direct sunlight, which might promote deterioration in tape or adhesion performance. The product is recommended to be used within 24 months after shipment. Extended shelf life over this period require a solderability check before use.

HANDLING

Chip capacitors are dense, hard, brittle, and abrasive materials. They are liable to suffer mechanical damage, in the form of cracks or chips. Chip Capacitors should be handled with care to avoid contamination or damage. To use vacuum or plastic tweezers to pick up or plastic tweezers is recommended for manual placement. Tape and reeled packages are suitable for automatic pick and placement machine.

PREHEAT

In order to minimize the risk of thermal shock during soldering, a carefully controlled preheat is required.

The rate of preheat should not exceed 3°C per second.

SOLDERING FLUX

Use mildly activated rosin RA and RMA fluxes, but do not use activated flux. The amount of solder in each solder joint should be controlled to prevent the damage of chip capacitors caused by the stress between solder, chips, and substrate.

SOLDERING TYPE

Lead containing solders, such as Sn60, Sn62 or Sn63 and lead free solders, such as SnAgCu, can all be used with our MLCCs.

In case of non-magnetic termination code "C", use lead containing or lead (Pb)-free SAC305 solders.

SOLDERING HEIGHT

The solder climbing minimum height is suggesting to 25% of chip thickness or 500um whichever is less.

(Reference from IPC-610E)

COOLING

After soldering, cool the chips and the substrate gradually to room temperature. Natural cooling in air is recommended to minimize stress in the solder joint.

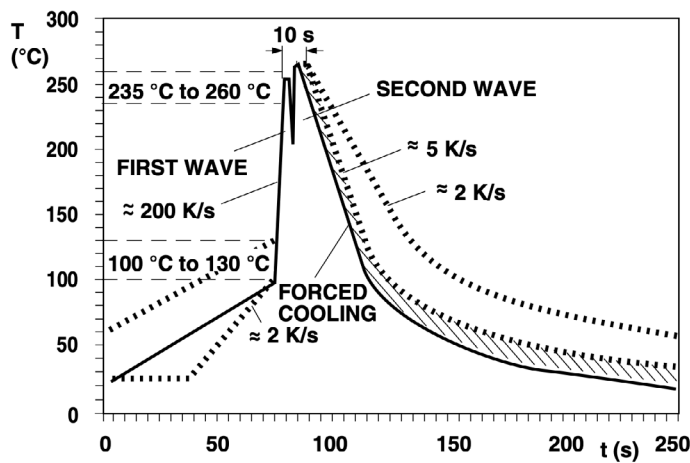
CLEANING

All flux residues must be removed by using suitable electronic-grade vapor-cleaning solvents to eliminate contamination that could cause electrolytic surface corrosion. Good results can be obtained by using ultrasonic cleaning of the solvent. The choice of the proper system is depends upon many factors such as component mix, flux, and solder paste and assembly method. The ability of the cleaning system to remove flux residues and contamination from under the chips is very important.

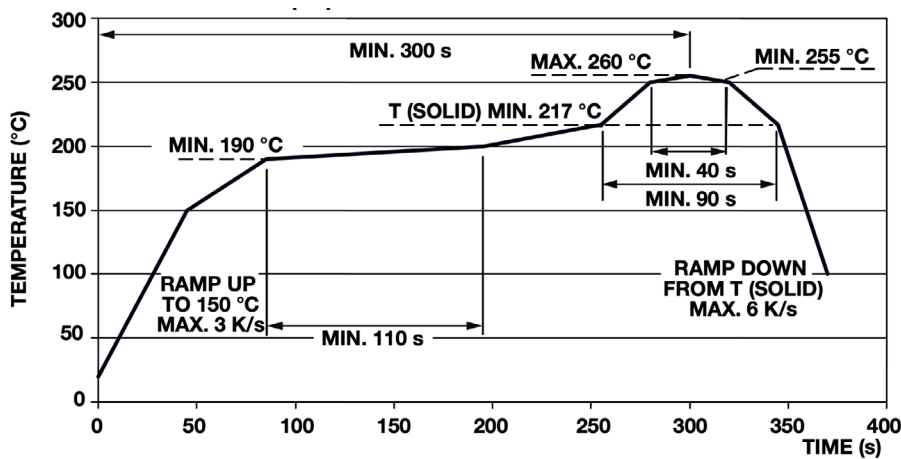
SOLDERING CONDITIONS

SIZE	THICKNESS	WAVE	REFLOW
0402	All	0	0
0505	All	0	0
0603	All	0	0
0805	< 1.25mm	0	0
0805	≥ 1.25mm		0
1111	< 1.25mm	0	0
1111	≥ 1.25mm		0
1206	< 1.25mm	0	0
1206	≥ 1.25mm		0
1210	< 1.25mm	0	0
1210	≥ 1.25mm		0
larger than 1210	All		0

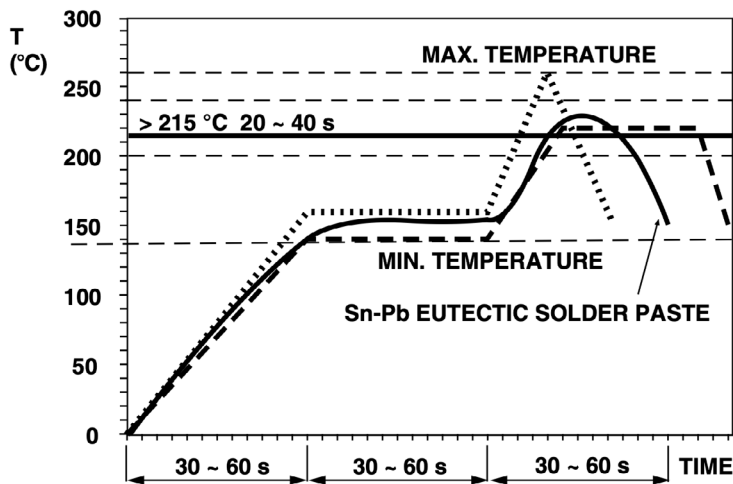
WAVE SOLDERING PROFILE



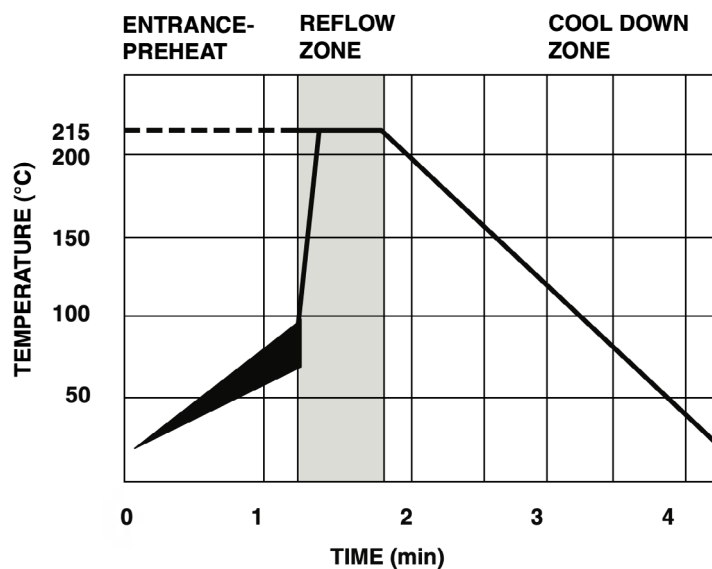
LEADFREE REFLOW SOLDERING PROFILE



SNI



VAPOUR PHASE REFLOW PROFILE



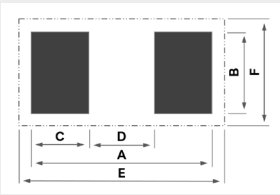
HAND SOLDERING

Hand soldering is not recommended as the thermal shock may cause a crack, however if used the following recommendations should be taken :

- Soldering iron tip diameter ≤ 3.0 mm and wattage max. 20W.
- The Capacitors shall be pre-heated to 150°C and that the temperature gradient between the devices and the tip of the soldering iron.
- Tip temperature $\leq 280^\circ\text{C}$ and should't be applied for more than 5 seconds.
- The required amount of solder shall be melted on the soldering tip.
- The tip of iron should not contact the ceramic body directly.
- The Capacitors shall be cooled gradually at room temperature after soldering.
- Forced air cooling is not allowed.

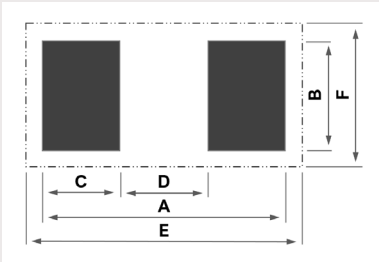
TYPICAL SMD FOOTPRINT WAVE SOLDERING

SIZE	FOOTPRINT DIMENSIONS IN MM					
	A	B	C	D	E	F
0603	2.40	0.80	0.70	1.00	3.10	1.40
0805	3.20	1.30	0.90	1.40	4.10	1.85
1206	4.80	1.70	1.25	2.30	5.90	2.25
1210	4.80	2.60	1.25	2.30	5.90	3.15



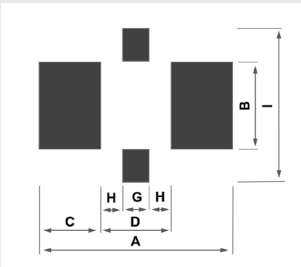
TYPICAL SMD FOOTPRINT REFLOW SOLDERING

SIZE	FOOTPRINT DIMENSIONS IN mm					
	A	B	C	D	E	F
0201	0.65	0.30	0.21	0.23	0.90	0.60
0204	1.00	1.00	0.30	0.40	1.25	1.45
0402	1.50	0.50	0.40	0.70	1.75	0.95
0306	1.30	1.60	0.40	0.50	1.55	2.05
0404	1.50	1.00	0.40	0.70	1.75	1.45
0504	1.90	1.00	0.40	1.10	2.15	1.45
0505	1.90	1.30	0.50	0.80	2.15	1.75
0508	1.90	2.00	0.50	0.90	2.15	2.55
0603	2.30	0.80	0.60	1.10	2.55	1.35
0612	2.30	3.20	0.60	1.10	2.55	3.75
0805	2.90	1.25	0.90	1.10	3.15	1.80
1206	4.10	1.60	0.90	2.30	4.35	2.25
1210	4.10	2.50	1.00	2.10	4.35	3.15
1808	5.50	2.10	1.20	3.10	5.75	2.75
1812	5.50	3.30	1.20	3.10	5.75	3.95
1825	5.50	6.55	1.20	3.10	5.75	7.20
2211	6.80	3.00	1.40	4.00	7.05	3.65
2220	6.80	5.40	1.40	4.00	7.05	6.05
2225	6.80	6.70	1.65	3.50	7.05	7.50
2525	7.70	6.75	1.65	4.40	7.95	7.55
2825	8.40	6.70	1.65	5.10	8.65	7.50
3033	9.00	8.80	1.95	5.10	9.25	9.60
3640	10.55	10.70	2.35	5.85	10.80	11.50
4040	11.60	10.70	2.35	6.90	11.85	11.50
40100	11.60	26.20	2.35	6.90	11.85	27.00
5550	15.50	13.20	2.35	10.80	15.75	14.00
6080	16.70	20.80	2.35	12.00	16.95	21.60
6660	18.30	15.70	2.35	13.60	18.55	16.50
8060	21.90	15.70	2.35	17.20	22.15	16.50
80150	21.90	38.90	2.35	17.20	22.15	39.70



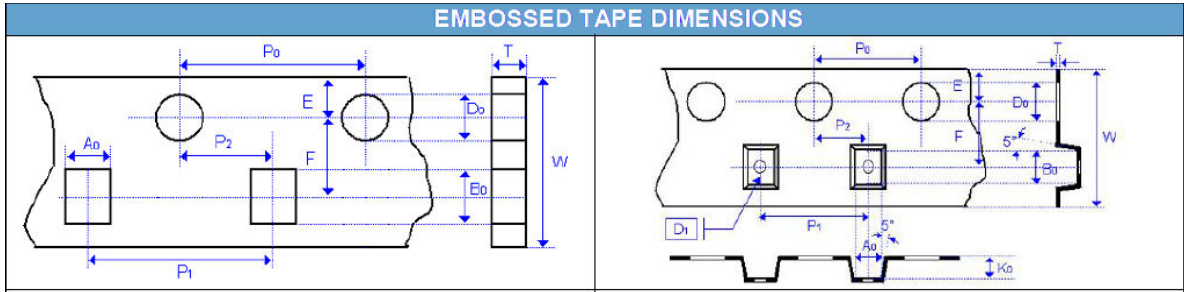
TYPICAL FILTER FOOTPRINT REFLOW SOLDERING

SIZE	FOOTPRINT DIMENSIONS IN mm						
	A	B	C	D	G	H	I
0603	2.30	0.80	0.45	1.40	0.60	0.40	1.50
0805	2.90	1.25	0.90	1.80	0.80	0.50	2.00
1206	4.10	1.60	0.90	2.40	1.00	0.70	3.00
1806	5.50	1.60	1.20	3.20	1.00	1.10	3.00
1812	5.50	3.30	1.20	3.90	1.50	1.20	4.80
2220	6.80	5.40	1.40	4.50	1.50	1.50	7.00

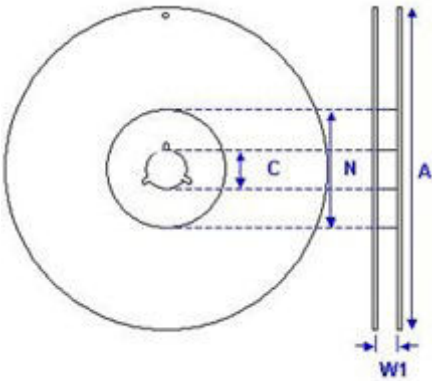


PACKAGE DIMENSION AND QUANTITY

SIZE	THICKNESS	PAPER TAPE		PLASTIC TAPE	
		7" REEL	13" REEL	7" REEL	13" REEL
0402	0.5 ± 0.05	10 K	50 K		
0504	0.6 ± 0.05			4K	15K
	0.9 ± 0.05			4K	15K
0603	0.7 ± 0.07	4K		4K	15K
	0.9 ± 0.07	4K	15K	4K	15K
	0.9 ± 0.07			4K	15K
	1.1 ± 0.07			4K	15K
0805	0.8 ± 0.07	4K	15K	4K	15K
	0.9 ± 0.07			4K	10K
	1.1 ± 0.07			3K	10K
	1.3 ± 0.07			3K	10K
1206	1.1 ± 0.1			3K	10K
	1.4 ± 0.1			3K	8K
	1.8 ± 0.1			2K	8K
1210	1.4 ± 0.1			3K	8K
	1.8 ± 0.1			1K	6K
1803	1.4 ± 0.1			3K	8K
1812	1.6 ± 0.1			2K	8K
	2.1 ± 0.1			1K	6K
	2.8 ± 0.1			1K	6K
2220	1.8 ± 0.1			1K	6K
	3.0 ± 0.1			0.5K	2K
2225	3.0 ± 0.1			0.5K	2K
3033	3.0 ± 0.1			0.5K	2K
3640	3.0 ± 0.1			0.5K	2K
5440	3.9 ± 0.1				0.5K - 1K



REEL SIZE	7"	7"	13"
C	13.0 +0.5/-0.2	13.0 +0.5/-0.2	13.0 +0.7/-0.3
W1	8.4 +1.5/-0	12.4 +2.0/-0	8.4 +2.0/-0
A	178.0 ±0.10	178.0 ±0.10	330.0 ±1.0
N	60.0 ±1.0	80.0 ±1.0	100 ±1.0



RELIABILITY PRINCIPLES OVERVIEW

In order to guarantee highly reliable products to their customers, we follow a strict quality policy which is explained below :

- According to AECQ philosophy, each component belongs to a family, which most restrictives members (four corners) have been fully qualified.
- PME components are produced in our Vendôme facility, with very stable process and equipments, in order to ensure Reliability and reproductibility.
- Reliability is based on batch tests, new product or equipment-specific qualifications and periodic requalifications.
- In addition to those regular tests, our quality departement launches regular accelerated tests to further deepens our reliability datas.
- Tests and qualifications of our standard products are based on AECQ methodology and are qualified according to the following limits.
- In accordance to AECQ methodology, specifics tests and limits can be adapted to fit our clients' needs.
- A whole range of stricter reliability tests can be offered for high Reliability products (burn-in, shocks, pulses...) for medical, space and defense applications.
- Based on our reliability database, FIT datas can be provided if necessary.

TESTING

Tests conducted during each batch

FREQUENCY	TEST/STRESS	REFERENCE	AEC-Q	DETAIL
100%	Capa, DF, IR	CECC-32100-4.6		according to datasheet
100%	Visual	CECC-32100-4.5	AEC-Q200-9	no visual defects
50/lot	DPA		AEC-Q200-5	internal component integrity
5/lot	Dimension	CECC-32100-4.5	AEC-Q200-5	according to datasheet
5/lot	Resistance to soldering heat	CECC-32100-4.10	AEC-Q200-15	
5/lot	Solderability	CECC-32100-4.11	AEC-Q200-18	
10/lot	Voltage proof	CECC-32100-4.6.4		
1/ceramic lot	Temperature coefficient	CECC 32100-Prgh4,7		according to datasheet

QUALIFICATIONS

Each component family has been qualified according to CECC and AECQ tests methodology, which are renewed on a periodic basis.

FREQUENCY	TEST/STRESS	REFERENCE	AEC-Q	DETAIL
Qualif	Electrical Characterization	CECC-32100-4.6 4.7	AEC-Q200-19	measure before test according to datasheet and after test according to post environmental limits
Qualif	Temperature Cycling	JESD22 Method-JA method 104	AEC-Q200-4	1,000 cycles -55°C to +125°C Measurement at 24 ± 2 hours after test conclusion
Qualif	Biased Humidity	MIL-STD-202 Method 103	AEC-Q200-7	1,000 hours 85°C/85%RH. Rated voltage. Measurement at 24 ± 2 hours after test conclusion
Qualif	Operational Life	MIL-STD-202 Method 108 condition D	AEC-Q200-8	1,000 hours at 125°C with applied Voltage : 2xRV RV≤500V, 1.2xRV 500V<RV≤1250V, RV RV>1250V
Qualif	High Temperature Exposure (Storage)	MIL-STD-202 Method 108	AEC-Q200-3	1,000 hours at 150°C with 0V. Measurement at 24 ± 2 hours after test conclusion
Qualif	Terminal Strength	CECC-32100-4.8	AEC-Q200-6	1.8kg 60 seconds
Qualif	Vibration	MIL-STD-202 Method 204	AEC-Q200-14	5g 20min 12cycles 3 orientations 10-2000Hz
Qualif	Board Flex	CEC 32100-4.9	AEC-Q200-21	3mm Type 1, 2mm Type 2, Measurement at 24 ± 2 hours after test conclusion

POST ENVIRONMENTAL STRESS LIMIT

DIELECTRIC	DISSIPATION FACTOR (MAXIMUM)	CAPACITANCE SHIFT	INSULATION RESISTANCE
NPO	≤ 4 10 ⁻³	±2%	10% initial limit
N2T	≤ 6 10 ⁻³	±4%	10% initial limit
X7R	≤ 0.035	±15%	10% initial limit

REACH Compliance



- We deliver non-chemical articles only.
- These contain no substances which are intended to be released under normal or reasonably foreseeable conditions of use according to Reach article 7(1).

We confirm hereby that our products contain none of the substances which are listed in the present candidate list of the European Chemicals Agency (ECHA), above a concentration of 0.1% by weight of the whole component.

Candidate list of substances (European Chemicals Agency ECHA) :
<http://echa.europa.eu/fr/candidate-list-table>

ROHS COMPLIANCE



We herewith confirm that RoHS-compliant products are conforming to the following EU directives:
EU directive 2015/863/EU EU directive 2011/65/EU EU directive 2003/11/EC

Following restricted materials are not used and do not exceed the legal limits: Lead (Pb, see exemptions),

- Mercury (Hg)
- Cadmium (Cd)
- Chromium (Cr VI)
- Polybrominated biphenyls (PBB) Polybrominated diphenyl ethers (PBDE) Bis(2-Ethylhexyl) phthalate (DEHP) Benzyl butyl phthalate (BBP)
- Dibutyl phthalate (DBP) Diisobutyl phthalate (DIBP)

Exemptions: The following exemptions according to the RoHS annexe are applicable:

Identity 7(a) :

- Lead in high melting temperature type solders (i.e. lead-based alloys containing 85% by weight or more lead).

Identity 7(c)-I :

- Electrical and electronic components containing lead in a glass or ceramic other than dielectric ceramic capacitors, e.g. piezoelectronic devices, or in a glass or ceramic matrix compound.

The components are suitable for a lead-free process according to EN 60068-2-58 and in accordance with the IPC/JEDEC standard J-Std-020D.
The lead free process has been tested using solder alloy Sn96.5Ag3Cu0.5

Export controls and dual-use regulations

Some components fall under 'dual-use' items under international export controls definition - those that can be used for civil or military purposes which meet certain specified technical standards.

The defining criteria for a dual use component is one with a voltage rating of >750Vdc and a capacitance value of >250nF when measured at 750Vdc and a series inductance <10nH. Components defined as dual-use under the above criteria may require a licence for export across international borders. Please contact us for further information on specific part numbers.

ISO9001:2015



In their design, research and development as well as the manufacturing of MLCC capacitors, customer service and distribution we use and maintain a Management System audited and certified in accordance to : **ISO9001:2015**

You may contact us for any inquiry regarding the regulations and compliance listed above.